

ABSTRACT OF THE DISCLOSURE

An electroless copper plating solution which is based on an electroless copper plating solution comprising a copper ion, a complexing agent, a hypophosphorous acid compound as a reducing agent, and a metallic catalyst for initiating a reductive reaction, as characterized by further comprising a lithium ion or both a lithium ion and a polyoxyethylene type surfactant, and a method for electroless copper plating using the same, as well as a plated product made by such a process. The electroless copper plating solution in the present invention enables a uniform and acicular copper film to be deposited on the surface of a plating object, and therefore can be used for improving the strength of adhesion between various metals and resins, including bonding of a copper foil to a resin as applied in a conductive circuit such as a multi-layer printed circuit board or in a copper-plated laminate.